

**US-PAT-NO:** 5930677  
**DOCUMENT-**  
**IDENTIFIER:** US 5930677 A  
**TITLE:** Method for reducing microloading in an etchback of spin-on-glass or polymer

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**TITLE - TI (1):**

Method for reducing microloading in an etchback of spin-on-glass or polymer

**Detailed Description Text - DETX (12):**

The process of the invention results in excellent planarization and uniformity of an interlevel dielectric layer with significantly reduced microloading effect at the spin-on-glass etchback step and elimination of keyhole defects. The addition of O.<sub>sub.2</sub> to the etchback plasma is much more than the extra release of oxygen when the first oxide layer is exposed; therefore, the microloading effect of the extra release of oxygen is greatly reduced by the process of the invention.